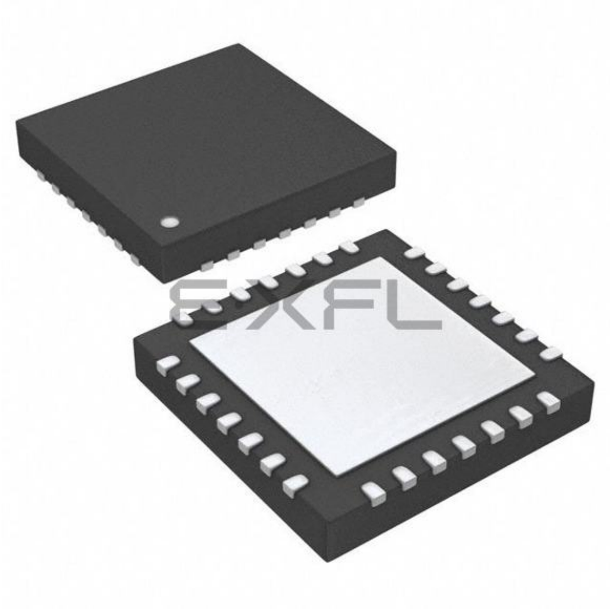
Microchip Technology - PIC18LF24K22T-I/ML Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	64MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	24
Program Memory Size	16KB (8K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 19x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf24k22t-i-ml

2.0 OSCILLATOR MODULE (WITH FAIL-SAFE CLOCK MONITOR)

2.1 Overview

The oscillator module has a wide variety of clock sources and selection features that allow it to be used in a wide range of applications while maximizing performance and minimizing power consumption. Figure 2-1 illustrates a block diagram of the oscillator module.

Clock sources can be configured from external oscillators, quartz crystal resonators, ceramic resonators and Resistor-Capacitor (RC) circuits. In addition, the system clock source can be configured from one of three internal oscillators, with a choice of speeds selectable via software. Additional clock features include:

- Selectable system clock source between external or internal sources via software.
- Two-Speed Start-up mode, which minimizes latency between external oscillator start-up and code execution.
- Fail-Safe Clock Monitor (FSCM) designed to detect a failure of the external clock source (LP, XT, HS, EC or RC modes) and switch automatically to the internal oscillator.
- Oscillator Start-up Timer (OST) ensures stability of crystal oscillator sources.

The primary clock module can be configured to provide one of six clock sources as the primary clock.

1.	RC	External Resistor/Capacitor
2.	LP	Low-Power Crystal
3.	XT	Crystal/Resonator
4.	INTOSC	Internal Oscillator
5.	HS	High-Speed Crystal/Resonator
6.	EC	External Clock

The HS and EC oscillator circuits can be optimized for power consumption and oscillator speed using settings in FOSC<3:0>. Additional FOSC<3:0> selections enable RA6 to be used as I/O or CLKO (FOSC/4) for RC, EC and INTOSC Oscillator modes.

Primary Clock modes are selectable by the FOSC<3:0> bits of the CONFIG1H Configuration register. The primary clock operation is further defined by these Configuration and register bits:

1. PRICLKEN (CONFIG1H<5>)
2. PRISD (OSCCON2<2>)
3. PLLCFG (CONFIG1H<4>)
4. PLLEN (OSCTUNE<6>)
5. HFOFST (CONFIG3H<3>)
6. IRCF<2:0> (OSCCON<6:4>)
7. MFIOSEL (OSCCON2<4>)
8. INTSRC (OSCTUNE<7>)

The HFINTOSC, MFINTOSC and LFINTOSC are factory calibrated high, medium and low-frequency oscillators, respectively, which are used as the internal clock sources.

4.0 RESET

The PIC18(L)F2X/4XK22 devices differentiate between various kinds of Reset:

a) Power-on Reset (POR)
b) $\overline{\text{MCLR}}$ Reset during normal operation
c) $\overline{\text{MCLR}}$ Reset during power-managed modes
d) Watchdog Timer (WDT) Reset (during execution)
e) Programmable Brown-out Reset (BOR)
f) RESET Instruction
g) Stack Full Reset
h) Stack Underflow Reset

This section discusses Resets generated by $\overline{\text{MCLR}}$, POR and BOR and covers the operation of the various start-up timers. Stack Reset events are covered in **Section 5.2.0.1 “Stack Full and Underflow Resets”**. WDT Resets are covered in **Section 24.3 “Watchdog Timer (WDT)”**.

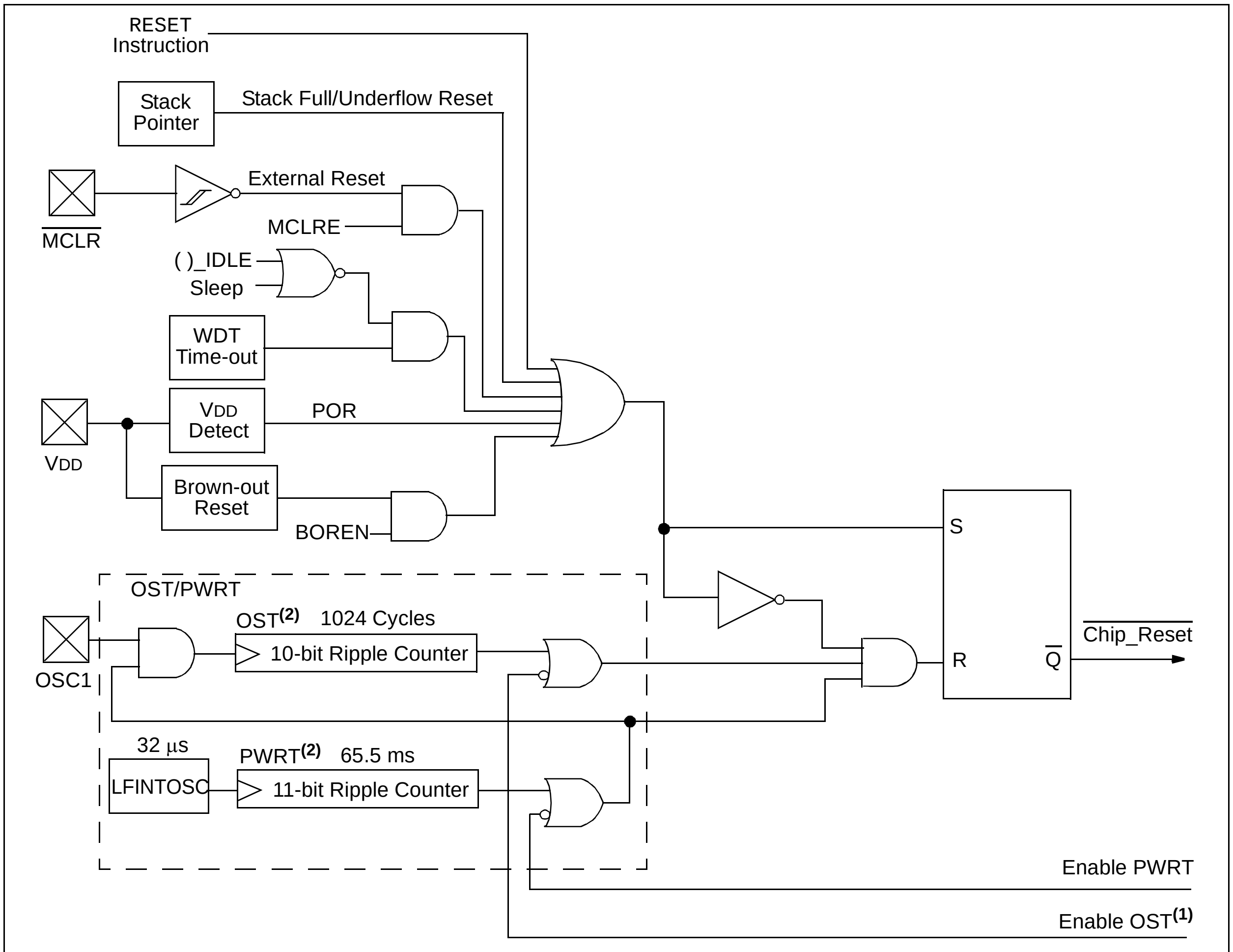
A simplified block diagram of the On-Chip Reset Circuit is shown in Figure 4-1.

4.1 RCON Register

Device Reset events are tracked through the RCON register (Register 4-1). The lower five bits of the register indicate that a specific Reset event has occurred. In most cases, these bits can only be cleared by the event and must be set by the application after the event. The state of these flag bits, taken together, can be read to indicate the type of Reset that just occurred. This is described in more detail in **Section 4.7 “Reset State of Registers”**.

The RCON register also has control bits for setting interrupt priority (IPEN) and software control of the BOR (SBOREN). Interrupt priority is discussed in **Section 9.0 “Interrupts”**. BOR is covered in **Section 4.5 “Brown-out Reset (BOR)”**.

FIGURE 4-1: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



Note 1: See Table 4-2 for time-out situations.

2: PWRT and OST counters are reset by POR and BOR. See Sections 4.4 and 4.5.

5.4.2 ACCESS BANK

While the use of the BSR with an embedded 8-bit address allows users to address the entire range of data memory, it also means that the user must always ensure that the correct bank is selected. Otherwise, data may be read from or written to the wrong location. This can be disastrous if a GPR is the intended target of an operation, but an SFR is written to instead. Verifying and/or changing the BSR for each read or write to data memory can become very inefficient.

To streamline access for the most commonly used data memory locations, the data memory is configured with an Access Bank, which allows users to access a mapped block of memory without specifying a BSR. The Access Bank consists of the first 96 bytes of memory (00h-5Fh) in Bank 0 and the last 160 bytes of memory (60h-FFh) in Block 15. The lower half is known as the “Access RAM” and is composed of GPRs. This upper half is also where the device’s SFRs are mapped. These two areas are mapped contiguously in the Access Bank and can be addressed in a linear fashion by an 8-bit address (Figures 5-5 through 5-7).

The Access Bank is used by core PIC18 instructions that include the Access RAM bit (the ‘a’ parameter in the instruction). When ‘a’ is equal to ‘1’, the instruction uses the BSR and the 8-bit address included in the opcode for the data memory address. When ‘a’ is ‘0’, however, the instruction is forced to use the Access Bank address map; the current value of the BSR is ignored entirely.

Using this “forced” addressing allows the instruction to operate on a data address in a single cycle, without updating the BSR first. For 8-bit addresses of 60h and above, this means that users can evaluate and operate on SFRs more efficiently. The Access RAM below 60h is a good place for data values that the user might need to access rapidly, such as immediate computational results or common program variables. Access RAM also allows for faster and more code efficient context saving and switching of variables.

The mapping of the Access Bank is slightly different when the extended instruction set is enabled (XINST Configuration bit = 1). This is discussed in more detail in **Section 5.7.3 “Mapping the Access Bank in Indexed Literal Offset Mode”**.

5.4.3 GENERAL PURPOSE REGISTER FILE

PIC18 devices may have banked memory in the GPR area. This is data RAM, which is available for use by all instructions. GPRs start at the bottom of Bank 0 (address 000h) and grow upwards towards the bottom of the SFR area. GPRs are not initialized by a Power-on Reset and are unchanged on all other Resets.

5.4.4 SPECIAL FUNCTION REGISTERS

The Special Function Registers (SFRs) are registers used by the CPU and peripheral modules for controlling the desired operation of the device. These registers are implemented as static RAM. SFRs start at the top of data memory (FFFh) and extend downward to occupy the top portion of Bank 15 (F38h to FFFh). A list of these registers is given in Table 5-1 and Table 5-2.

The SFRs can be classified into two sets: those associated with the “core” device functionality (ALU, Resets and interrupts) and those related to the peripheral functions. The Reset and interrupt registers are described in their respective chapters, while the ALU’s STATUS register is described later in this section. Registers related to the operation of a peripheral feature are described in the chapter for that peripheral.

The SFRs are typically distributed among the peripherals whose functions they control. Unused SFR locations are unimplemented and read as ‘0’s.

TABLE 5-1: SPECIAL FUNCTION REGISTER MAP FOR PIC18(L)F2X/4XK22 DEVICES

Address	Name	Address	Name	Address	Name	Address	Name	Address	Name
FFFh	TOSU	FD7h	TMR0H	FAFh	SPBRG1	F87h	—[2]	F5Fh	CCPR3H
FFEh	TOSH	FD6h	TMR0L	FAEh	RCREG1	F86h	—[2]	F5Eh	CCPR3L
FFDh	TOSL	FD5h	T0CON	FADh	TXREG1	F85h	—[2]	F5Dh	CCP3CON
FFCh	STKPTR	FD4h	—[2]	FACh	TXSTA1	F84h	PORTE	F5Ch	PWM3CON
FFBh	PCLATU	FD3h	OSCCON	FABh	RCSTA1	F83h	PORTD[3]	F5Bh	ECCP3AS
FFAh	PCLATH	FD2h	OSCCON2	FAAh	EEADRH[4]	F82h	PORTC	F5Ah	PSTR3CON
FF9h	PCL	FD1h	WDTCON	FA9h	EEADR	F81h	PORTB	F59h	CCPR4H
FF8h	TBLPTRU	FD0h	RCON	FA8h	EEDATA	F80h	PORTA	F58h	CCPR4L
FF7h	TBLPTRH	FCFh	TMR1H	FA7h	EECON2[1]	F7Fh	IPR5	F57h	CCP4CON
FF6h	TBLPTRL	FCEh	TMR1L	FA6h	EECON1	F7Eh	PIR5	F56h	CCPR5H
FF5h	TABLAT	FCDh	T1CON	FA5h	IPR3	F7Dh	PIE5	F55h	CCPR5L
FF4h	PRODH	FCCh	T1GCON	FA4h	PIR3	F7Ch	IPR4	F54h	CCP5CON
FF3h	PRODL	FCBh	SSP1CON3	FA3h	PIE3	F7Bh	PIR4	F53h	TMR4
FF2h	INTCON	FCAh	SSP1MSK	FA2h	IPR2	F7Ah	PIE4	F52h	PR4
FF1h	INTCON2	FC9h	SSP1BUF	FA1h	PIR2	F79h	CM1CON0	F51h	T4CON
FF0h	INTCON3	FC8h	SSP1ADD	FA0h	PIE2	F78h	CM2CON0	F50h	TMR5H
FEFh	INDF0[1]	FC7h	SSP1STAT	F9Fh	IPR1	F77h	CM2CON1	F4Fh	TMR5L
FEEh	POSTINC0[1]	FC6h	SSP1CON1	F9Eh	PIR1	F76h	SPBRGH2	F4Eh	T5CON
FEDh	POSTDEC0[1]	FC5h	SSP1CON2	F9Dh	PIE1	F75h	SPBRG2	F4Dh	T5GCON
FECh	PREINC0[1]	FC4h	ADRESH	F9Ch	HLVDCON	F74h	RCREG2	F4Ch	TMR6
FEBh	PLUSW0[1]	FC3h	ADRESL	F9Bh	OSCTUNE	F73h	TXREG2	F4Bh	PR6
FEAh	FSR0H	FC2h	ADCON0	F9Ah	—[2]	F72h	TXSTA2	F4Ah	T6CON
FE9h	FSR0L	FC1h	ADCON1	F99h	—[2]	F71h	RCSTA2	F49h	CCPTMRS0
FE8h	WREG	FC0h	ADCON2	F98h	—[2]	F70h	BAUDCON2	F48h	CCPTMRS1
FE7h	INDF1[1]	FBFh	CCPR1H	F97h	—[2]	F6Fh	SSP2BUF	F47h	SRCON0
FE6h	POSTINC1[1]	FBEh	CCPR1L	F96h	TRISE	F6Eh	SSP2ADD	F46h	SRCON1
FE5h	POSTDEC1[1]	FBDh	CCP1CON	F95h	TRISD[3]	F6Dh	SSP2STAT	F45h	CTMUCONH
FE4h	PREINC1[1]	FBCh	TMR2	F94h	TRISC	F6Ch	SSP2CON1	F44h	CTMUCONL
FE3h	PLUSW1[1]	FBBh	PR2	F93h	TRISB	F6Bh	SSP2CON2	F43h	CTMUICON
FE2h	FSR1H	FBAh	T2CON	F92h	TRISA	F6Ah	SSP2MSK	F42h	VREFCON0
FE1h	FSR1L	FB9h	PSTR1CON	F91h	—[2]	F69h	SSP2CON3	F41h	VREFCON1
FE0h	BSR	FB8h	BAUDCON1	F90h	—[2]	F68h	CCPR2H	F40h	VREFCON2
FDFh	INDF2[1]	FB7h	PWM1CON	F8Fh	—[2]	F67h	CCPR2L	F3Fh	PMD0
FDEh	POSTINC2[1]	FB6h	ECCP1AS	F8Eh	—[2]	F66h	CCP2CON	F3Eh	PMD1
FDDh	POSTDEC2[1]	FB5h	—[2]	F8Dh	LATE[3]	F65h	PWM2CON	F3Dh	PMD2
FDCh	PREINC2[1]	FB4h	T3GCON	F8Ch	LATD[3]	F64h	ECCP2AS	F3Ch	ANSELE
FDBh	PLUSW2[1]	FB3h	TMR3H	F8Bh	LATC	F63h	PSTR2CON	F3Bh	ANSELD
FDAh	FSR2H	FB2h	TMR3L	F8Ah	LATB	F62h	IOCB	F3Ah	ANSELC
FD9h	FSR2L	FB1h	T3CON	F89h	LATA	F61h	WPUB	F39h	ANSELB
FD8h	STATUS	FB0h	SPBRGH1	F88h	—[2]	F60h	SLRCON	F38h	ANSELA

Note 1: This is not a physical register.

2: Unimplemented registers are read as '0'.

3: PIC18(L)F4XK22 devices only.

4: PIC18(L)F26K22 and PIC18(L)F46K22 devices only.

REGISTER 9-17: IPR4: PERIPHERAL INTERRUPT PRIORITY REGISTER 4

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	CCP5IP	CCP4IP	CCP3IP
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7-3 **Unimplemented:** Read as ‘0’

bit 2 **CCP5IP:** CCP5 Interrupt Priority bit
1 = High priority
0 = Low priority

bit 1 **CCP4IP:** CCP4 Interrupt Priority bit
1 = High priority
0 = Low priority

bit 0 **CCP3IP:** CCP3 Interrupt Priority bit
1 = High priority
0 = Low priority

REGISTER 9-18: IPR5: PERIPHERAL INTERRUPT PRIORITY REGISTER 5

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	TMR6IP	TMR5IP	TMR4IP
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7-3 **Unimplemented:** Read as ‘0’

bit 2 **TMR6IP:** TMR6 to PR6 Match Interrupt Priority bit
1 = High priority
0 = Low priority

bit 1 **TMR5IP:** TMR5 Overflow Interrupt Priority bit
1 = High priority
0 = Low priority

bit 0 **TMR4IP:** TMR4 to PR4 Match Interrupt Priority bit
1 = High priority
0 = Low priority

12.1 Timer1/3/5 Operation

The Timer1/3/5 module is a 16-bit incrementing counter which is accessed through the TMRxH:TMRxL register pair. Writes to TMRxH or TMRxL directly update the counter.

When used with an internal clock source, the module is a timer and increments on every instruction cycle. When used with an external clock source, the module can be used as either a timer or counter and increments on every selected edge of the external source.

Timer1/3/5 is enabled by configuring the TMRxON and TMRxGE bits in the TxCON and TxGCON registers, respectively. Table 12-1 displays the Timer1/3/5 enable selections.

TABLE 12-1: TIMER1/3/5 ENABLE SELECTIONS

TMRxON	TMRxGE	Timer1/3/5 Operation
0	0	Off
0	1	Off
1	0	Always On
1	1	Count Enabled

12.2 Clock Source Selection

The TMRxCS<1:0> and TxSOSCEN bits of the TxCON register are used to select the clock source for Timer1/3/5. The dedicated Secondary Oscillator circuit can be used as the clock source for Timer1, Timer3 and Timer5, simultaneously. Any of the TxSOSCEN bits will enable the Secondary Oscillator circuit and select it as the clock source for that particular timer. Table 12-2 displays the clock source selections.

12.2.1 INTERNAL CLOCK SOURCE

When the internal clock source is selected the TMRxH:TMRxL register pair will increment on multiples of FOSC as determined by the Timer1/3/5 prescaler.

When the FOSC internal clock source is selected, the Timer1/3/5 register value will increment by four counts every instruction clock cycle. Due to this condition, a 2 LSB error in resolution will occur when reading the Timer1/3/5 value. To utilize the full resolution of Timer1/3/5, an asynchronous input signal must be used to gate the Timer1/3/5 clock input.

The following asynchronous sources may be used:

- Asynchronous event on the TxG pin to Timer1/3/5 Gate
- C1 or C2 comparator input to Timer1/3/5 Gate

12.2.2 EXTERNAL CLOCK SOURCE

When the external clock source is selected, the Timer1/3/5 module may work as a timer or a counter.

When enabled to count, Timer1/3/5 is incremented on the rising edge of the external clock input of the TxCKI pin. This external clock source can be synchronized to the microcontroller system clock or it can run asynchronously.

When used as a timer with a clock oscillator, an external 32.768 kHz crystal can be used in conjunction with the dedicated secondary internal oscillator circuit.

> **Note:** In Counter mode, a falling edge must be registered by the counter prior to the first incrementing rising edge after any one or more of the following conditions:
>
> - Timer1/3/5 enabled after POR
> - Write to TMRxH or TMRxL
> - Timer1/3/5 is disabled
> - Timer1/3/5 is disabled (TMRxON = 0) when TxCKI is high then Timer1/3/5 is enabled (TMRxON=1) when TxCKI is low.

TABLE 12-2: CLOCK SOURCE SELECTIONS

TMRxCS1	TMRxCS0	TxSOSCEN	Clock Source
0	1	x	System Clock (FOSC)
0	0	x	Instruction Clock (FOSC/4)
1	0	0	External Clocking on TxCKI Pin
1	0	1	Osc.Circuit On SOSCI/SOSCO Pins

15.5.6 CLOCK STRETCHING

Clock stretching occurs when a device on the bus holds the SCLx line low effectively pausing communication. The slave may stretch the clock to allow more time to handle data or prepare a response for the master device. A master device is not concerned with stretching as anytime it is active on the bus and not transferring data it is stretching. Any stretching done by a slave is invisible to the master software and handled by the hardware that generates SCLx.

The CKP bit of the SSPxCON1 register is used to control stretching in software. Any time the CKP bit is cleared, the module will wait for the SCLx line to go low and then hold it. Setting CKP will release SCLx and allow more communication.

15.5.6.1 Normal Clock Stretching

Following an $\overline{\text{ACK}}$ if the R/$\overline{\text{W}}$ bit of SSPxSTAT is set, a read request, the slave hardware will clear CKP. This allows the slave time to update SSPxBUF with data to transfer to the master. If the SEN bit of SSPxCON2 is set, the slave hardware will always stretch the clock after the $\overline{\text{ACK}}$ sequence. Once the slave is ready; CKP is set by software and communication resumes.

Note 1: The BF bit has no effect on whether the clock will be stretched or not. This is different than previous versions of the module that would not stretch the clock, clear CKP, if SSPxBUF was read before the 9th falling edge of SCLx.

2: Previous versions of the module did not stretch the clock for a transmission if SSPxBUF was loaded before the 9th falling edge of SCLx. It is now always cleared for read requests.

15.5.6.2 10-bit Addressing Mode

In 10-bit Addressing mode, when the UA bit is set, the clock is always stretched. This is the only time the SCLx is stretched without CKP being cleared. SCLx is released immediately after a write to SSPxADD.

Note: Previous versions of the module did not stretch the clock if the second address byte did not match.

15.5.6.3 Byte NACKing

When the AHEN bit of SSPxCON3 is set; CKP is cleared by hardware after the 8th falling edge of SCLx for a received matching address byte. When the DHEN bit of SSPxCON3 is set; CKP is cleared after the 8th falling edge of SCLx for received data.

Stretching after the 8th falling edge of SCLx allows the slave to look at the received address or data and decide if it wants to ACK the received data.

15.5.7 CLOCK SYNCHRONIZATION AND THE CKP BIT

Any time the CKP bit is cleared, the module will wait for the SCLx line to go low and then hold it. However, clearing the CKP bit will not assert the SCLx output low until the SCLx output is already sampled low. Therefore, the CKP bit will not assert the SCLx line until an external I^{2}C master device has already asserted the SCLx line. The SCLx output will remain low until the CKP bit is set and all other devices on the I^{2}C bus have released SCLx. This ensures that a write to the CKP bit will not violate the minimum high time requirement for SCLx (see Figure 15-23).

FIGURE 15-23: CLOCK SYNCHRONIZATION TIMING

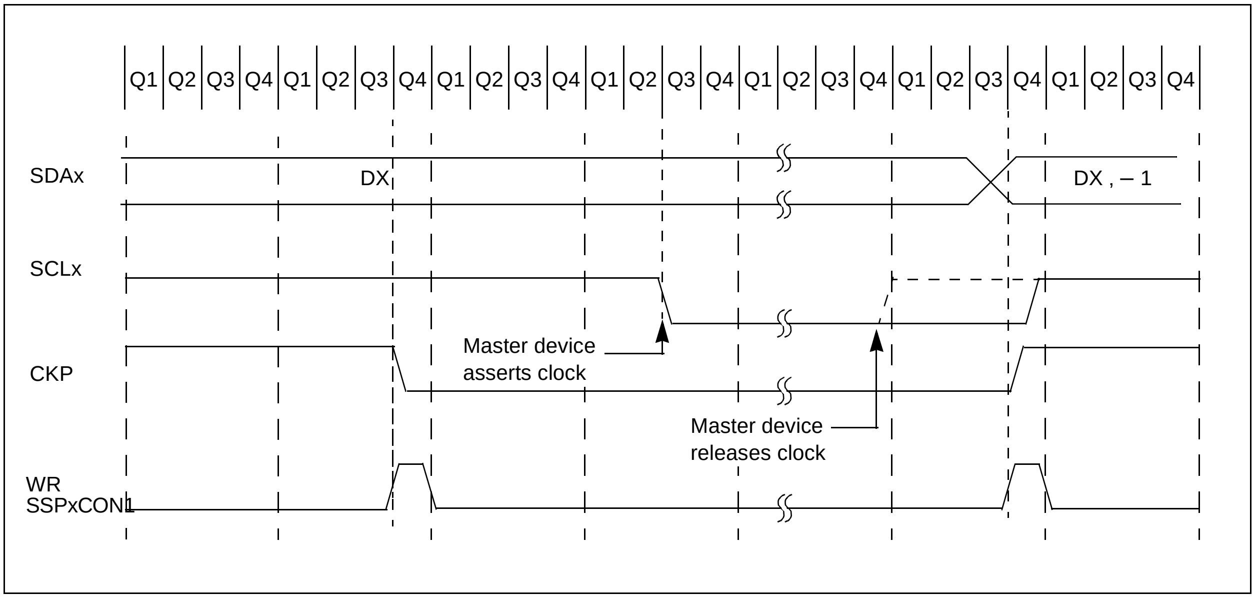
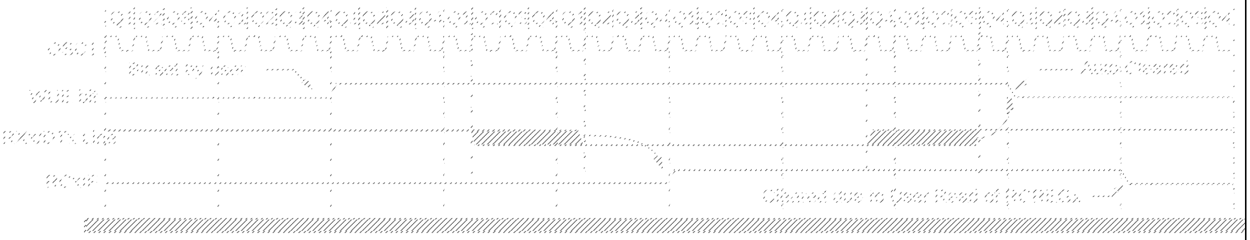
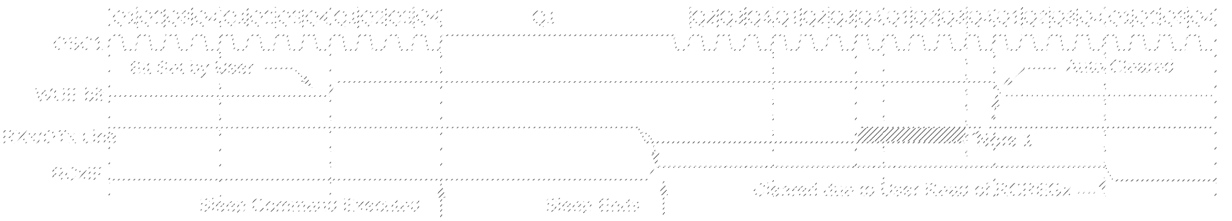

Q1 Q2 Q3 Q4 Q1 Q2 Q3 Q4 Q1 Q2 Q3 Q4 Q1 Q2 Q3 Q4 Q1 Q2 Q3 Q4 Q1 Q2 Q3 Q4 Q1 Q2 Q3 Q4
SDAx
DX
DX , – 1
SCLx
CKP
Master device asserts clock
Master device releases clock
WR SSPxCON1

FIGURE 16-7: AUTO-WAKE-UP BIT (WUE) TIMING DURING NORMAL OPERATION



Note 1: The EUSART remains in Idle while the WUE bit is set.

FIGURE 16-8: AUTO-WAKE-UP BIT (WUE) TIMINGS DURING SLEEP



Note 1: If the wake-up event requires long oscillator warm-up time, the automatic clearing of the WUE bit can occur while the stposc signal is still active. This sequence should not depend on the presence of Q clocks.

2: The EUSART remains in Idle while the WUE bit is set.

23.7 Operation During Sleep

When enabled, the HLVD circuitry continues to operate during Sleep. If the device voltage crosses the trip point, the HLVDIF bit will be set and the device will wake-up from Sleep. Device execution will continue from the interrupt vector address if interrupts have been globally enabled.

23.8 Effects of a Reset

A device Reset forces all registers to their Reset state. This forces the HLVD module to be turned off.

TABLE 23-1: REGISTERS ASSOCIATED WITH HIGH/LOW-VOLTAGE DETECT MODULE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on page
HLVDCON	VDIRMAG	BGVST	IRVST	HLVDEN	HLVDL<3:0>				337
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	109
IPR2	OSCFIP	C1IP	C2IP	EEIP	BCL1IP	HLVDIP	TMR3IP	CCP2IP	122
PIE2	OSCFIE	C1IE	C2IE	EEIE	BCL1IE	HLVDIE	TMR3IE	CCP2IE	118
PIR2	OSCFIF	C1IF	C2IF	EEIF	BCL1IF	HLVDIF	TMR3IF	CCP2IF	113
TRISA	TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	151

Legend: — = unimplemented locations, read as ‘0’. Shaded bits are unused by the HLVD module.

ADDWFC ADD W and CARRY bit to f

Syntax: ADDWFC f {,d {,a}}

Operands: $0 \leq f \leq 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (W) + (f) + (C) → dest

Status Affected: N,OV, C, DC, Z

Encoding:

`0010`	`00da`	`ffff`	`ffff`

Description: Add W, the CARRY flag and data memory location ‘f’. If ‘d’ is ‘`0`’, the result is placed in W. If ‘d’ is ‘`1`’, the result is placed in data memory location ‘f’.
If ‘a’ is ‘`0`’, the Access Bank is selected. If ‘a’ is ‘`1`’, the BSR is used to select the GPR bank.
If ‘a’ is ‘`0`’ and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 25.2.3 “Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode”** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register ‘f’	Process Data	Write to destination

Example: `ADDWFC REG, 0, 1`

Before Instruction

CARRY bit	=	1
REG	=	02h
W	=	4Dh

After Instruction

CARRY bit	=	0
REG	=	02h
W	=	50h

ANDLW AND literal with W

Syntax: ANDLW k

Operands: $0 \leq k \leq 255$

Operation: (W) .AND. k → W

Status Affected: N, Z

Encoding:

`0000`	`1011`	`kkkk`	`kkkk`

Description: The contents of W are AND’ed with the 8-bit literal ‘k’. The result is placed in W.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal ‘k’	Process Data	Write to W

Example: `ANDLW 05Fh`

Before Instruction

W = A3h

After Instruction

W = 03h

BNOV Branch if Not Overflow

Syntax: BNOV n

Operands: -128 ≤ n ≤ 127

Operation: if OVERFLOW bit is '0'
(PC) + 2 + 2n → PC

Status Affected: None

Encoding:

1110	0101	nnnn	nnnn

Description: If the OVERFLOW bit is '0', then the program will branch.
The 2's complement number '2n' is added to the PC. Since the PC will have incremented to fetch the next instruction, the new address will be PC + 2 + 2n. This instruction is then a 2-cycle instruction.

Words: 1

Cycles: 1(2)

Q Cycle Activity:
If Jump:

Q1	Q2	Q3	Q4
Decode	Read literal 'n'	Process Data	Write to PC
No operation	No operation	No operation	No operation

If No Jump:

Q1	Q2	Q3	Q4
Decode	Read literal 'n'	Process Data	No operation

Example: HERE BNOV Jump

```
Before Instruction
    PC          =  address (HERE)
After Instruction
    If OVERFLOW =  0;
       PC       =  address (Jump)
    If OVERFLOW =  1;
       PC       =  address (HERE + 2)
```

BNZ Branch if Not Zero

Syntax: BNZ n

Operands: -128 ≤ n ≤ 127

Operation: if ZERO bit is '0'
(PC) + 2 + 2n → PC

Status Affected: None

Encoding:

1110	0001	nnnn	nnnn

Description: If the ZERO bit is '0', then the program will branch.
The 2's complement number '2n' is added to the PC. Since the PC will have incremented to fetch the next instruction, the new address will be PC + 2 + 2n. This instruction is then a 2-cycle instruction.

Words: 1

Cycles: 1(2)

Q Cycle Activity:
If Jump:

Q1	Q2	Q3	Q4
Decode	Read literal 'n'	Process Data	Write to PC
No operation	No operation	No operation	No operation

If No Jump:

Q1	Q2	Q3	Q4
Decode	Read literal 'n'	Process Data	No operation

Example: HERE BNZ Jump

```
Before Instruction
    PC          =  address (HERE)
After Instruction
    If ZERO     =  0;
       PC       =  address (Jump)
    If ZERO     =  1;
       PC       =  address (HERE + 2)
```

BTFSC Bit Test File, Skip if Clear

Syntax: BTFSC f, b {,a}

Operands: $0 \le f \le 255$
$0 \le b \le 7$
$a \in [0,1]$

Operation: skip if (f<b>) = 0

Status Affected: None

Encoding:

1011	bbba	ffff	ffff

Description: If bit ‘b’ in register ‘f’ is ‘0’, then the next instruction is skipped. If bit ‘b’ is ‘0’, then the next instruction fetched during the current instruction execution is discarded and a NOP is executed instead, making this a 2-cycle instruction.
If ‘a’ is ‘0’, the Access Bank is selected. If ‘a’ is ‘1’, the BSR is used to select the GPR bank.
If ‘a’ is ‘0’ and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 25.2.3 “Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode”** for details.

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register ‘f’	Process Data	No operation

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:

```
HERE    BTFSC   FLAG, 1, 0
FALSE   :
TRUE    :
```

Before Instruction
PC = address (HERE)
After Instruction
If FLAG<1> = 0;
PC = address (TRUE)
If FLAG<1> = 1;
PC = address (FALSE)

BTFSS Bit Test File, Skip if Set

Syntax: BTFSS f, b {,a}

Operands: $0 \le f \le 255$
$0 \le b < 7$
$a \in [0,1]$

Operation: skip if (f<b>) = 1

Status Affected: None

Encoding:

1010	bbba	ffff	ffff

Description: If bit ‘b’ in register ‘f’ is ‘1’, then the next instruction is skipped. If bit ‘b’ is ‘1’, then the next instruction fetched during the current instruction execution is discarded and a NOP is executed instead, making this a 2-cycle instruction.
If ‘a’ is ‘0’, the Access Bank is selected. If ‘a’ is ‘1’, the BSR is used to select the GPR bank.
If ‘a’ is ‘0’ and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 25.2.3 “Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode”** for details.

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register ‘f’	Process Data	No operation

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:

```
HERE    BTFSS   FLAG, 1, 0
FALSE   :
TRUE    :
```

Before Instruction
PC = address (HERE)
After Instruction
If FLAG<1> = 0;
PC = address (FALSE)
If FLAG<1> = 1;
PC = address (TRUE)

DECFSZ	Decrement f, skip if 0
Syntax:	DECFSZ f {,d {,a}}
Operands:	0 ≤ f ≤ 255 d ∈ [0,1] a ∈ [0,1]
Operation:	(f) – 1 → dest, skip if result = 0
Status Affected:	None

Encoding:

0010	11da	ffff	ffff

Description: The contents of register 'f' are decremented. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed back in register 'f' (default).
If the result is '0', the next instruction, which is already fetched, is discarded and a NOP is executed instead, making it a 2-cycle instruction.
If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 25.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:

```
HERE       DECFSZ   CNT, 1, 1
           GOTO     LOOP
CONTINUE
```

Before Instruction
PC = Address (HERE)
After Instruction
CNT = CNT - 1
If CNT = 0;
PC = Address (CONTINUE)
If CNT ≠ 0;
PC = Address (HERE + 2)

DCFSNZ	Decrement f, skip if not 0
Syntax:	DCFSNZ f {,d {,a}}
Operands:	0 ≤ f ≤ 255 d ∈ [0,1] a ∈ [0,1]
Operation:	(f) – 1 → dest, skip if result ≠ 0
Status Affected:	None

Encoding:

0100	11da	ffff	ffff

Description: The contents of register 'f' are decremented. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed back in register 'f' (default).
If the result is not '0', the next instruction, which is already fetched, is discarded and a NOP is executed instead, making it a 2-cycle instruction.
If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 25.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:

```
HERE    DCFSNZ  TEMP, 1, 0
ZERO    :
NZERO   :
```

Before Instruction
TEMP = ?
After Instruction
TEMP = TEMP – 1,
If TEMP = 0;
PC = Address (ZERO)
If TEMP ≠ 0;
PC = Address (NZERO)

27.6 DC Characteristics: Primary Idle Supply Current, PIC18(L)F2X/4XK22

PIC18LF2X/4XK22		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +125°C					
PIC18F2X/4XK22		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +125°C					
Param No.	**Device Characteristics**	**Typ**	**Max**	**Units**	**Conditions**		
D100	Supply Current (IDD)(1),(2)	0.030	0.050	mA	-40°C to +125°C	VDD = 1.8V	Fosc = 1 MHz (**PRI_IDLE** mode, ECM source)
D101		0.045	0.065	mA	-40°C to +125°C	VDD = 3.0V	
D102		0.06	0.12	mA	-40°C to +125°C	VDD = 2.3V	Fosc = 1 MHz (**PRI_IDLE** mode, ECM source)
D103		0.08	0.15	mA	-40°C to +125°C	VDD = 3.0V	
D104		0.13	0.20	mA	-40°C to +125°C	VDD = 5.0V	
D105		0.45	0.8	mA	-40°C to +125°C	VDD = 1.8V	Fosc = 20 MHz (**PRI_IDLE** mode, ECH source)
D106		0.70	1.0	mA	-40°C to +125°C	VDD = 3.0V	
D107		0.55	0.8	mA	-40°C to +125°C	VDD = 2.3V	Fosc = 20 MHz (**PRI_IDLE** mode, ECH source)
D108		0.75	1.0	mA	-40°C to +125°C	VDD = 3.0V	
D109		0.90	1.2	mA	-40°C to +125°C	VDD = 5.0V	
D110		2.25	3.0	mA	-40°C to +125°C	VDD = 3.0V	Fosc = 64 MHz (**PRI_IDLE** mode, ECH source)
D111		2.25	3.0	mA	-40°C to +125°C	VDD = 3.0V	Fosc = 64 MHz (**PRI_IDLE** mode, ECH source)
D112		2.60	3.5	mA	-40°C to +125°C	VDD = 5.0V	
D113		0.35	0.6	mA	-40°C to +125°C	VDD = 1.8V	Fosc = 4 MHz 16 MHz Internal (**PRI_IDLE** mode, ECM + PLL source)
D114		0.55	0.8	mA	-40°C to +125°C	VDD = 3.0V	
D115		0.45	0.6	mA	-40°C to +125°C	VDD = 2.3V	Fosc = 4 MHz 16 MHz Internal (**PRI_IDLE** mode, ECM + PLL source)
D116		0.60	0.9	mA	-40°C to +125°C	VDD = 3.0V	
D117		0.70	1.0	mA	-40°C to +125°C	VDD = 5.0V	
D118		2.2	3.0	mA	-40°C to +125°C	VDD = 3.0V	Fosc = 16 MHz 64 MHz Internal (**PRI_IDLE** mode, ECH + PLL source)
D119		2.2	3.0	mA	-40°C to +125°C	VDD = 3.0V	Fosc = 16 MHz 64 MHz Internal (**PRI_IDLE** mode, ECH + PLL source)
D120		2.5	3.5	mA	-40°C to +125°C	VDD = 5.0V	

Note 1: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
Test condition: All Peripheral Module Control bits in PMD0, PMD1 and PMD2 set to ‘1’.

2: The test conditions for all IDD measurements in active operation mode are:
All I/O pins set as outputs driven to Vss;
MCLR = VDD;
OSC1 = external square wave, from rail-to-rail (PRI_RUN and PRI_IDLE only).

27.7 DC Characteristics: Secondary Oscillator Supply Current, PIC18(L)F2X/4XK22

PIC18LF2X/4XK22		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C					
PIC18F2X/4XK22		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C					
Param No.	Device Characteristics	Typ	Max	Units	Conditions		
D130	Supply Current (IDD)(1),(2)	3.5	23	μA	-40°C	VDD = 1.8V	Fosc = 32 kHz (**SEC_RUN** mode, SOSC source)
		3.7	25	μA	+25°C		
		3.8	—	μA	+60°C		
		4.0	28	μA	+85°C		
		5.1	30	μA	+125°C		
D131		6.2	26	μA	-40°C	VDD = 3.0V	
		6.4	30	μA	+25°C		
		6.5	—	μA	+60°C		
		6.8	35	μA	+85°C		
		7.8	40	μA	+125°C		
D132		15	35	μA	-40°C	VDD = 2.3V	Fosc = 32 kHz (**SEC_RUN** mode, SOSC source)
		16	35	μA	+25°C		
		17	35	μA	+85°C		
		19	50	μA	+125°C		
D133		18	50	μA	-40°C	VDD = 3.0V	
		19	50	μA	+25°C		
		21	50	μA	+85°C		
		22	60	μA	+125°C		
D134		19	55	μA	-40°C	VDD = 5.0V	
		20	55	μA	+25°C		
		22	55	μA	+85°C		
		23	70	μA	+125°C		

Note 1: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
Test condition: All Peripheral Module Control bits in PMD0, PMD1 and PMD2 set to ‘1’.

2: The test conditions for all IDD measurements in active operation mode are:
All I/O pins set as outputs driven to Vss;
$\overline{\text{MCLR}}$ = VDD;
SOSCI / SOSCO = complementary external square wave, from rail-to-rail.

FIGURE 28-22: PIC18F2X/4XK22 TYPICAL IDD: RC_RUN LF-INTOSC 31 kHz

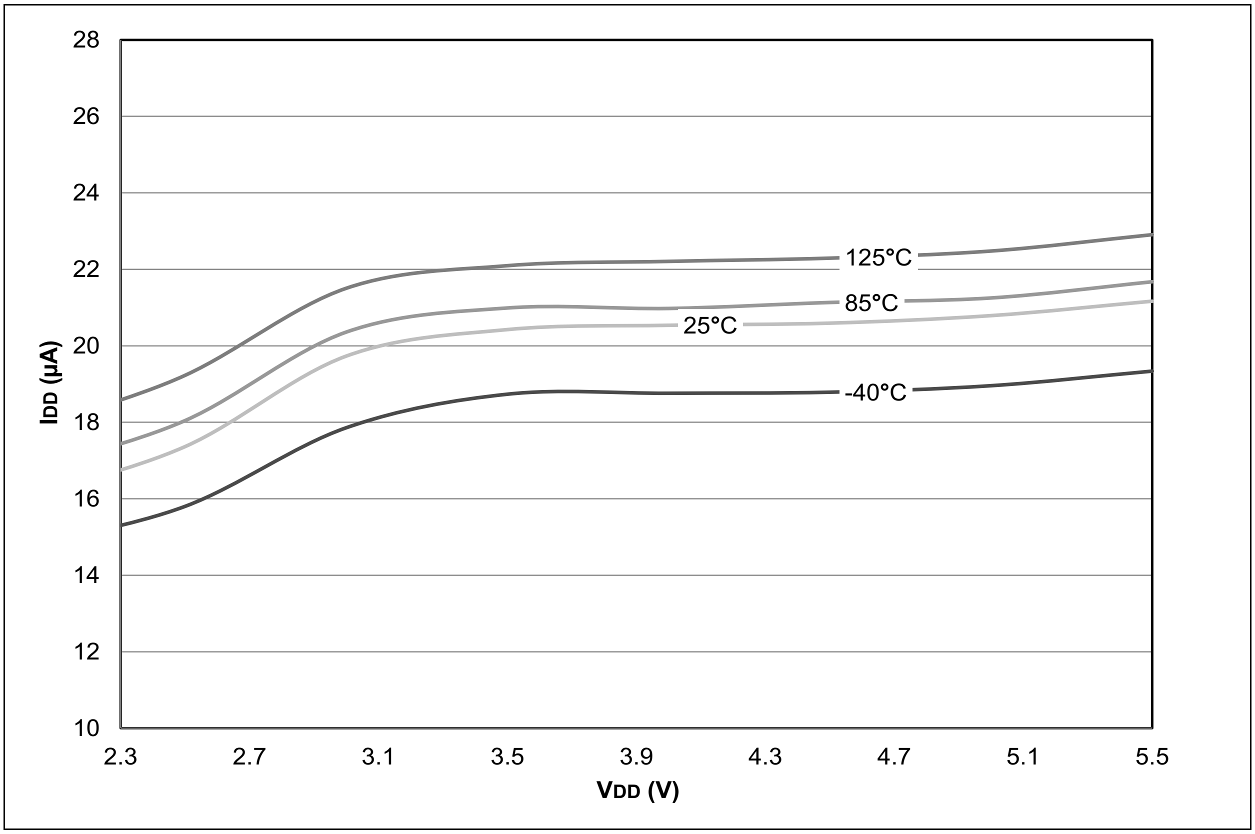


FIGURE 28-23: PIC18F2X/4XK22 MAXIMUM IDD: RC_RUN LF-INTOSC 31 kHz

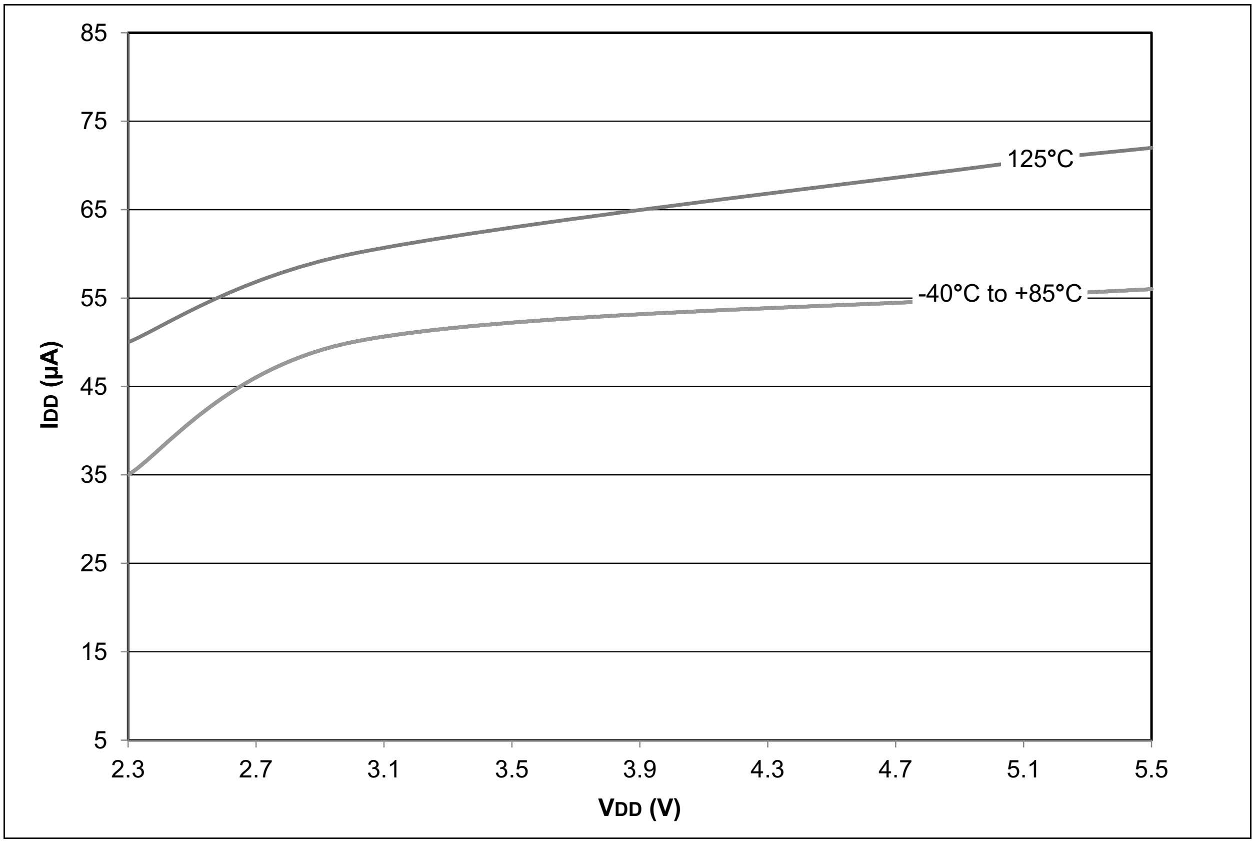


FIGURE 28-74: PIC18F2X/4XK22 TYPICAL IDD: SEC_RUN 32.768 kHz

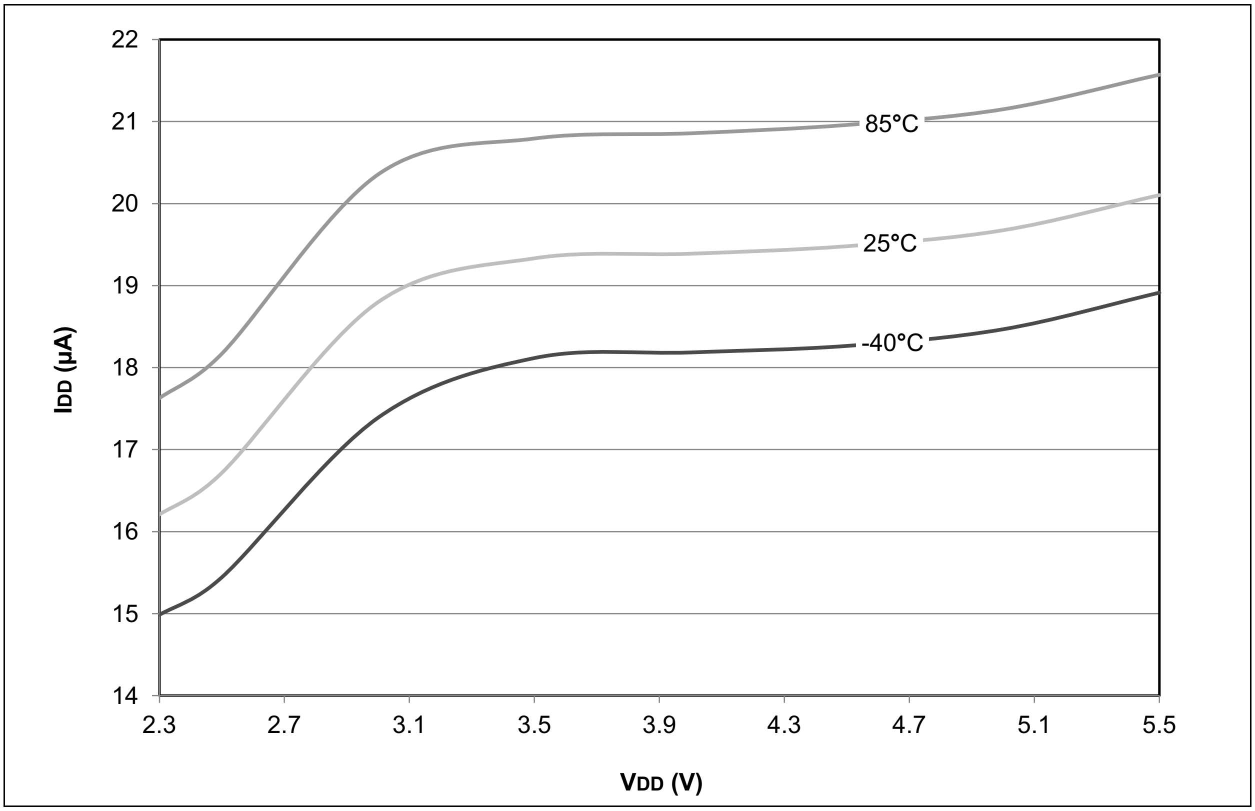


FIGURE 28-75: PIC18F2X/4XK22 MAXIMUM IDD: SEC_RUN 32.768 kHz

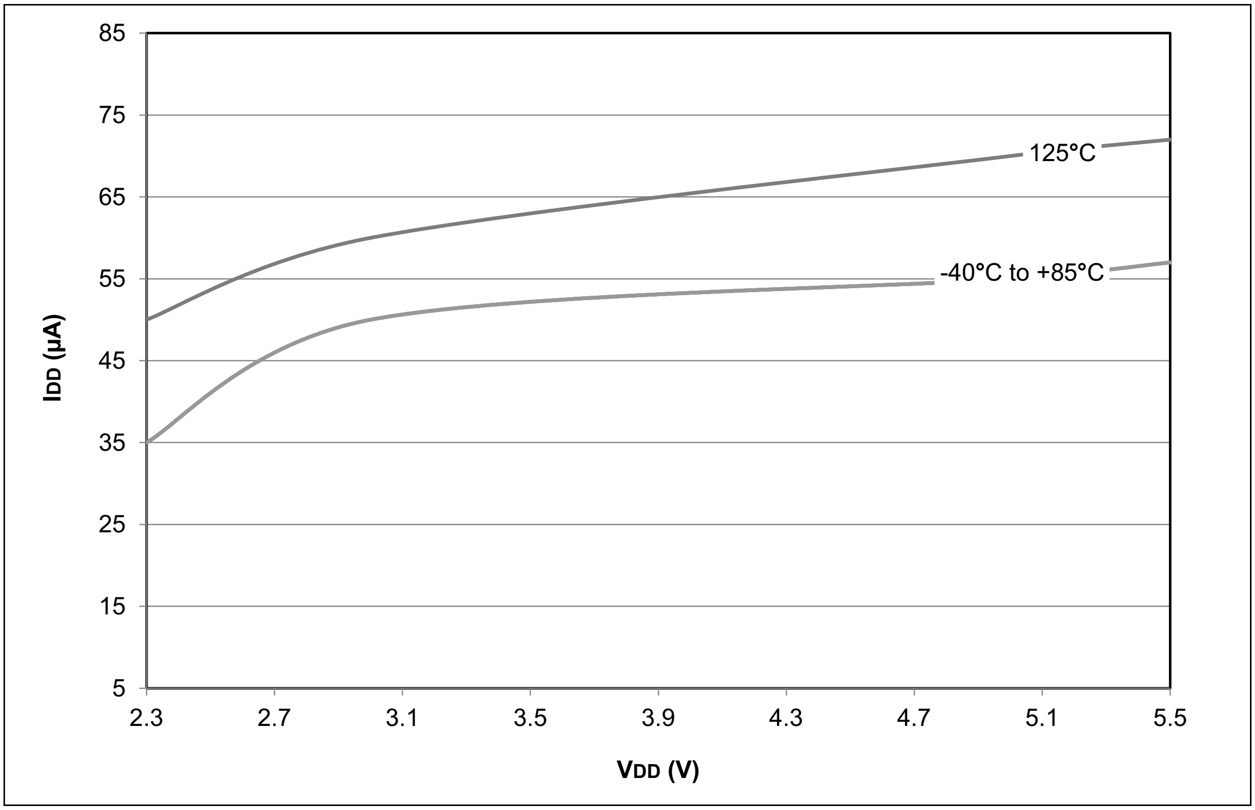


FIGURE 28-78: PIC18F2X/4XK22 TYPICAL IDD: SEC_IDLE 32.768 kHz

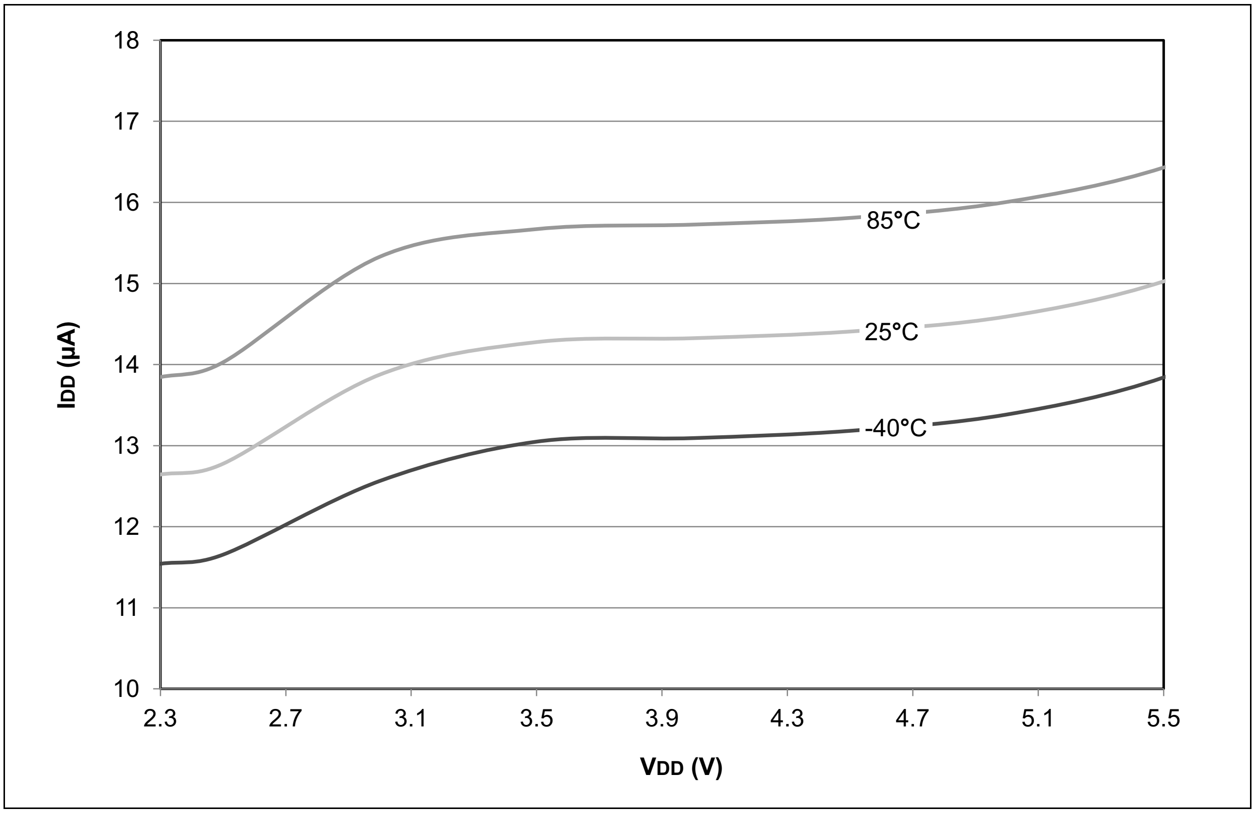


FIGURE 28-79: PIC18F2X/4XK22 MAXIMUM IDD: SEC_IDLE 32.768 kHz

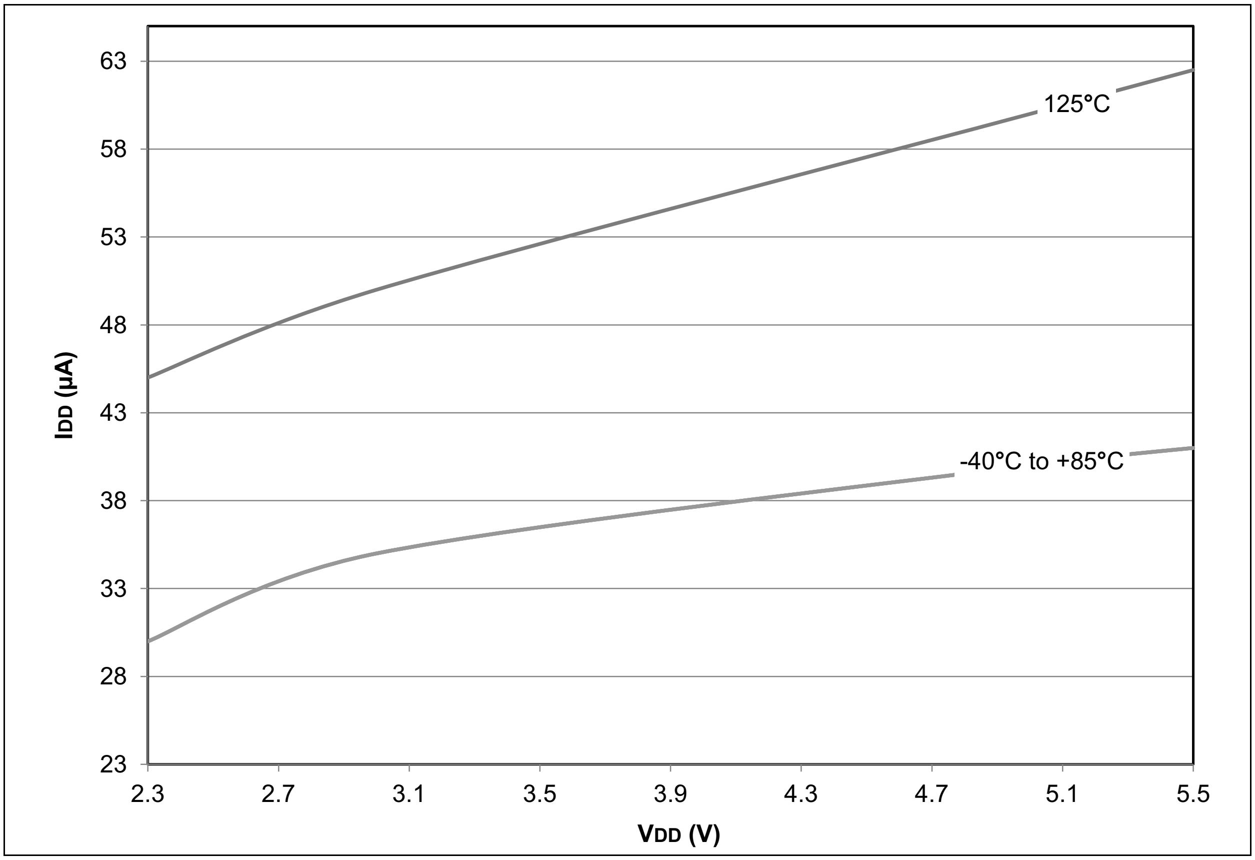
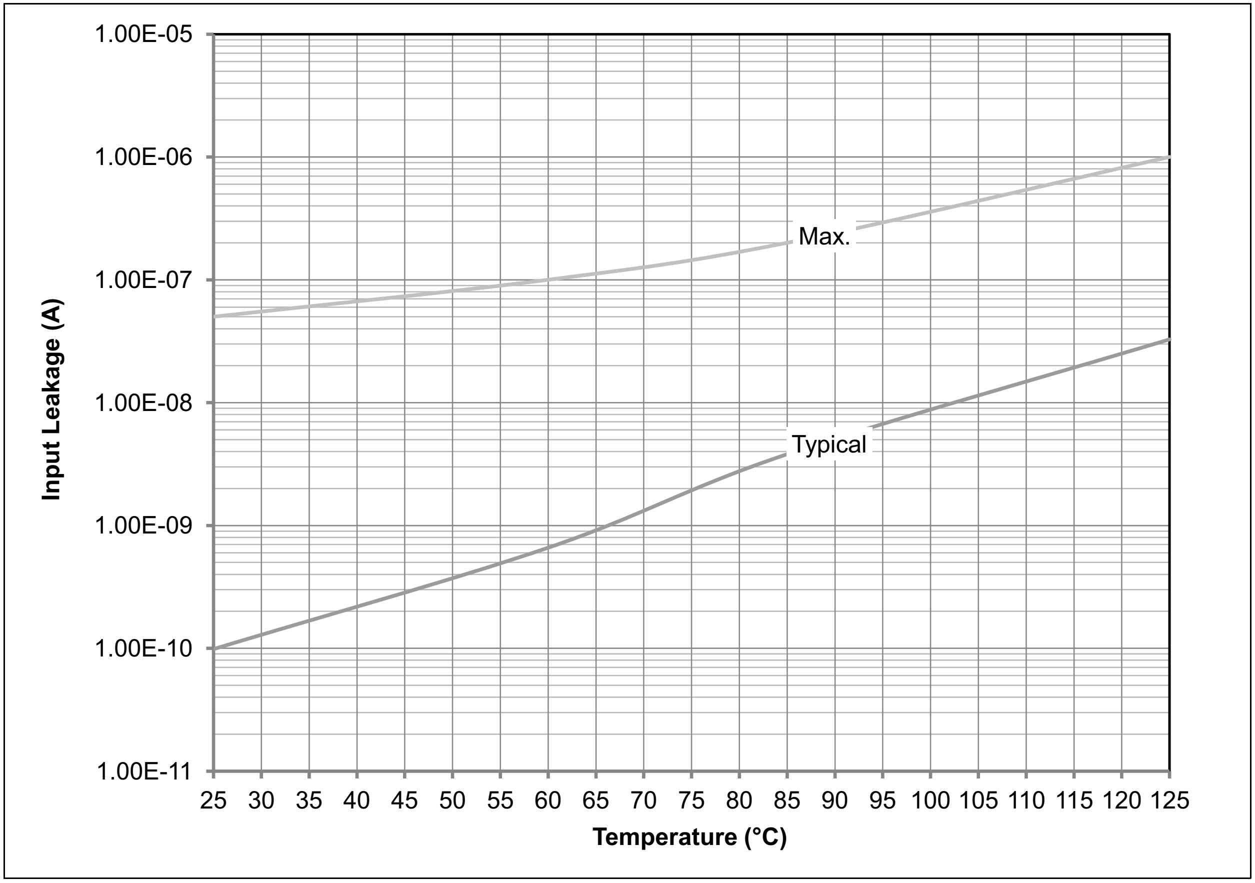


FIGURE 28-84: PIC18(L)F2X/4XK22 PIN INPUT LEAKAGE

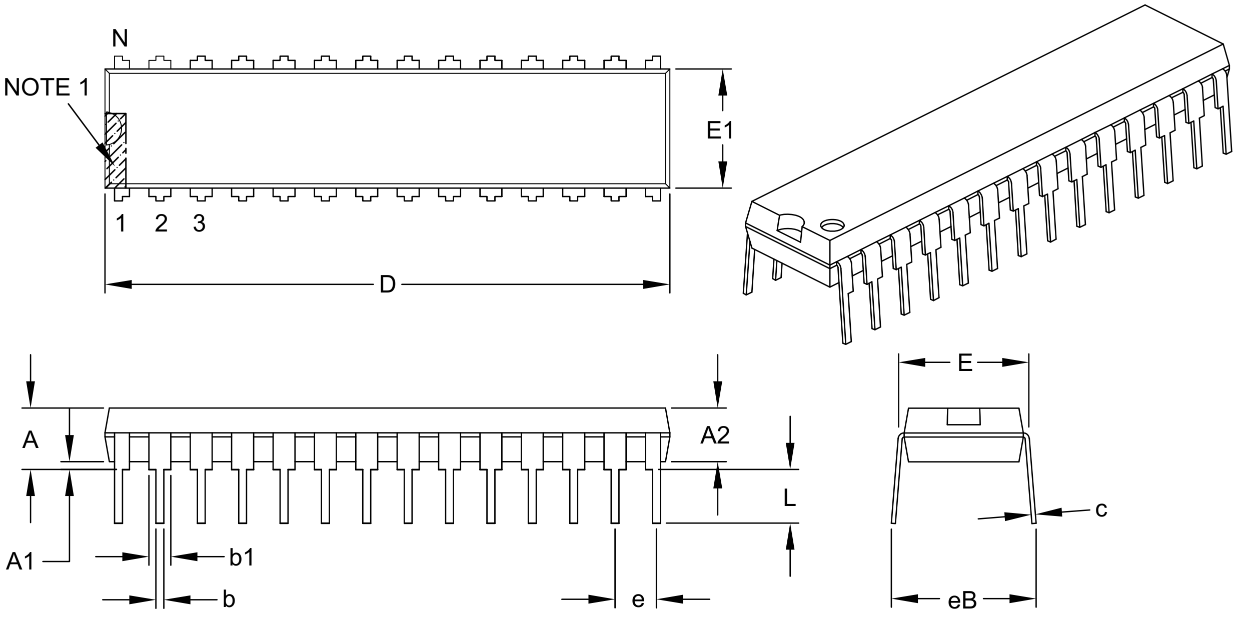


29.2 Package Details

The following sections give the technical details of the packages.

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

> **Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



		Units	INCHES	
	Dimension Limits	MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	.100 BSC		
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B